

## **RJR Polymers, Inc. announces Technology licensing agreement with Zentrix Technologies**

RJR Polymers, Inc. of Oakland California is pleased to announce that they have licensed RJR's Air Cavity Package technology to Zentrix Technologies of Newburyport, Massachusetts (A wholly own subsidiary of Brush Engineered Materials Inc. -NYSE:BW)

Zentrix designs and manufacturers electronic RF packages and components for the electronic packaging industry. Zentrix specializes in providing high quality metallizing, plating, and joining of ceramics and metals. Standard products include LDMOS packages, CuPack Direct Bond Copper (DBC) RF packages, and insulated electronic packages.

Commenting on the Agreement, Director of Sales and Marketing for RJR Polymers, Dave DeWire, stated that "this licensing agreement with Zentrix Technologies will afford our customers and the industry at large even greater access to this exciting LCP air cavity package technology. Customers who have felt apprehension over RJR's strong patent and single source position in this technology need no longer be concerned. RJR has found in Zentrix Technologies a knowledgeable and skilled licensee with compatible and complementary manufacturing processes that will assure our customers a steady, high quality second source of supply. We're pleased to have them on board and look forward to the continued growth of this product and market penetration this agreement will provide."

RJR Polymers Inc. is an integrated manufacturer of electronic packaging for the RF/ Wireless, telecom and optical imaging industries. RJR offers injected molded air cavity LCP packages, pre-applied epoxy lids and sealing equipment. RJR offers their customers a turnkey solution, providing all aspects of packages and prototype assembly. RJR specializes in SOIC, QFN, high power RF and custom packaging, flip chip lids, epoxies and hi-end sealing equipment.